

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT				
NATURE OF CONVEYANCE:	ASSIGNMENT				
CONVEYING PARTY DATA					
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shimpei TAKAGI</td> <td>10/04/2012</td> </tr> </tbody> </table>		Name	Execution Date	Shimpei TAKAGI	10/04/2012
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Shimpei TAKAGI	10/04/2012				
RECEIVING PARTY DATA					
Name:	Sumitomo Electric Industries, Ltd.				
Street Address:	5-33, Kitahama 4-chome, Chuo-ku				
City:	Osaka-shi, Osaka				
State/Country:	JAPAN				
Postal Code:	541-0041				
PROPERTY NUMBERS Total: 1					
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13567283</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13567283
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Application Number:	13567283				
CORRESPONDENCE DATA					
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Total Attachments: 1 source=assignment#page1.tif					

CH \$40.00 13567283

ASSIGNMENT

Whereas, I/we,

NameAddress1) **Shimpei TAKAGI**

c/o Osaka Works of Sumitomo Electric Industries, Ltd.,

1-3, Shimaya 1-chome, Konohana-ku,
Osaka-shi, Osaka 554-0024 Japan

hereinafter called assignor(s), have invented certain improvements in
METHOD FOR FABRICATING GROUP-III NITRIDE SEMICONDUCTOR LASER DEVICE

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on August 6, 2012, Serial No. 13/567283; and

Whereas

SUMITOMO ELECTRIC INDUSTRIES, LTD.
5-33, Kitahama 4-chome, Chuo-ku,
Osaka-shi, Osaka 541-0041 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORSDATE SIGNED

1):

*Shimpei TAKAGI**October 4, 2012*

Name:

Shimpei TAKAGI